



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D

** : Required Field*

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-02-06
Contact Name *	Refer to "Supplier Comment" section	Contact Title	Refer to "Supplier Comment" section
Contact Phone *	Refer to "Supplier Comment" section	Contact Email *	Refer to "Supplier Comment" section
Authorized Representative *	Antonella Lanzafame	Representative Title	AMG Materials Declaration Champion
Representative Phone *	Refer to "Supplier Comment" section	Representative Email *	Refer to "Supplier Comment" section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L7987LTR	BSIO*UI76ADA	A	ZY1A	2017-02-06
Amount		UoM	Unit type	ST ECOPACK Grade
59.40		mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used o	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	5X4.4X1	16	gull wing	
Comment	Package: HTSSOP 16 4.4 PITCH 0.65 EXPAD			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-12th January 2017				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	BSIO*UI76ADA					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Silicon die	Other inorganic materials	3.7	mg	supplier	die	Silicon (Si)	7440-21-3		3.487	mg	942432	58704
Silicon die				supplier	metallization	Aluminium (Al)	7429-90-5		0.036	mg	9730	606
Silicon die				supplier	metallization	Titanium Nitride (TiN)	25583-20-4		0.021	mg	5676	354
Silicon die				supplier	metallization	Tungsten (W)	7440-33-7		0.029	mg	7838	488
Silicon die				supplier	back side metallization	Chromium (Cr)	7440-47-3		0.003	mg	811	51
Silicon die				supplier	back side metallization	Gold (Au)	7440-57-5		0.007	mg	1892	118
Silicon die				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.012	mg	3243	202
Silicon die				supplier	back side metallization	Vanadium (V)	7440-62-2		0.001	mg	270	17
Silicon die				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.007	mg	1892	118
Silicon die				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.062	mg	16757	1044
Silicon die				supplier	passivation	PIX1 Gamma-butyrolactone	96-48-0		0.035	mg	9459	589
LEADFRAME	Copper and its alloy	25.243	mg	supplier	back side metallization	Gold (Au)	7440-57-5		0.007	mg	277	118
LEADFRAME				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.018	mg	713	303
LEADFRAME				supplier	back side metallization	Vanadium (V)	7440-62-2		0.002	mg	79	34
LEADFRAME				supplier	alloy	Copper (Cu)	7440-50-8		24.454	mg	968744	411684
LEADFRAME				supplier	alloy	Nickel(Ni)	7440-02-0		0.762	mg	30187	12828
DIE ATTACH	Other organic materials	0.809	mg	supplier	alloy	Silicon (Si)	7440-21-3		0.165	mg	203956	2778
DIE ATTACH				supplier	alloy	Magnesium(Mg)	7439-95-4		0.038	mg	46972	640
DIE ATTACH				supplier	metallization	Silver (Ag)	7440-22-4		0.596	mg	736712	10034
DIE ATTACH				supplier	glue	Epoxy resin	9003-36-5		0.002	mg	2472	34
DIE ATTACH				supplier	glue	Silver(Ag)	7440-22-4		0.007	mg	8653	118
DIE ATTACH				supplier	glue	Aromatic amineProprietary	Proprietary		0.001	mg	1236	17
BONDING WIRE	Other inorganic materials	0.526	mg	supplier	wire	Gold (Au)	7440-57-5		0.526	mg	1000000	8855
ENCAPSULATION	Other inorganic materials	27.671	mg	supplier	molding compound	Epoxy resin	25068-38-6		2.49	mg	89986	41919
ENCAPSULATION				supplier	molding compound	Silica fused (SiO2)	60676-86-0		23.244	mg	840013	391313
ENCAPSULATION				supplier	molding compound	Carbon Black	1333-86-4		0.138	mg	4987	2323
ENCAPSULATION				supplier	molding compound	Phenol Resin	29690-82-2		1.799	mg	65014	30286
FINISHING	Other inorganic materials	1.451	mg	supplier	connection coating	Tin (Sn)	7440-31-5		1.451	mg	1000000	24428